

Copper

SLOTOCOUP TF 1350

Copper SLOTOCOUP TF 1350 has especially been developed for the filling of through holes with an aspect ratio > 2.5 by Reverse Pulse Plating.
The copper coatings deposited from the Copper SLOTOCOUP TF 1350 are fine-grained and ductile with excellent metal distribution.

The electrolyte is made-up and operated with two additives. The electrolyte can be operated with soluble copper- or insoluble MMO anodes.
The plating parameters depend on the geometry and diameter of the through holes and must be adjusted individually.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

